

# NUCLEO144\_Q (int-SMPS)

MB1361

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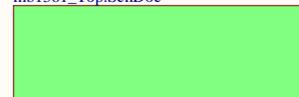
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U\_mb1361\_Top  
mb1361\_Top.SchDoc

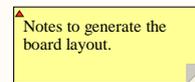


## Legend

General comment such as function title, configuration, ...

Text to be added to silkscreen.

Warning text.



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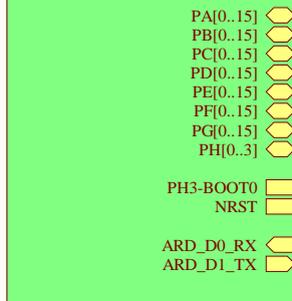
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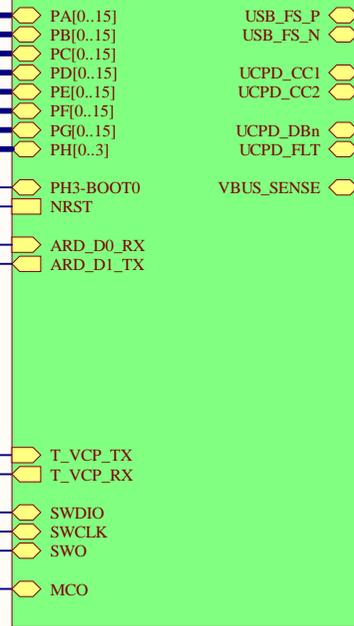
Title: <b>Project overview</b>	
Project: <b>NUCLEO144_Q (int-SMPS)</b>	
Variant: <b>L552ZEQ</b>	
Revision: <b>C-02</b>	Reference: <b>MB1361</b>
Size: <b>A4</b>	Date: <b>13-JUNE-19</b>
Sheet: <b>1</b> of <b>9</b>	



U\_ARDUINO\_extension\_connectors  
ARDUINO\_extension\_connectors.SchDoc



U\_STM32\_microcontroller\_IOs  
STM32\_microcontroller\_IOs.SchDoc



U\_USB\_Type\_C  
USB\_Type\_C.SchDoc



U\_STM32\_microcontroller\_power  
STM32\_microcontroller\_power.SchDoc



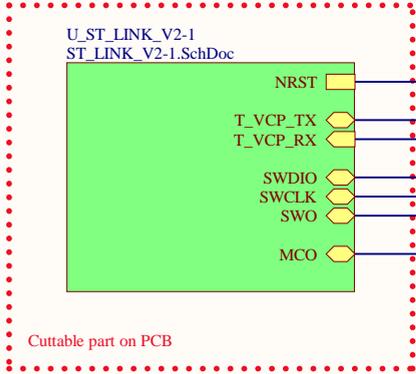
U\_POWER\_BOARD  
POWER\_BOARD.SchDoc



U\_Mechanical\_Parts  
Mechanical\_Parts.SchDoc

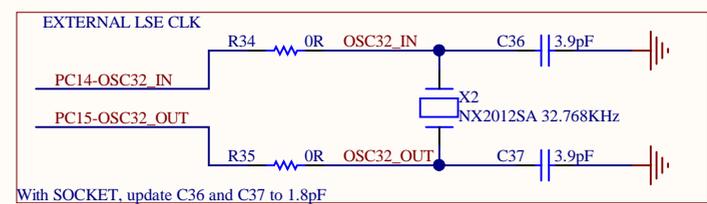
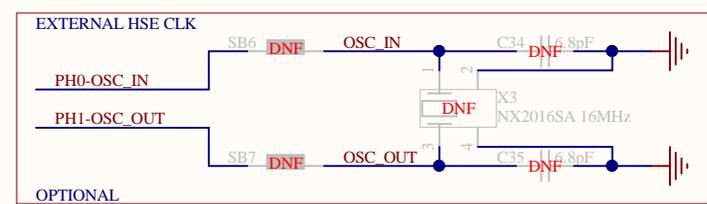
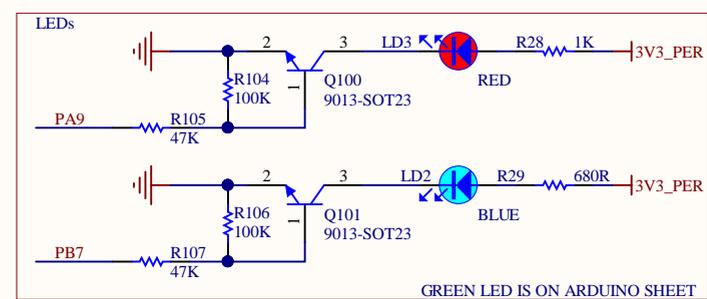
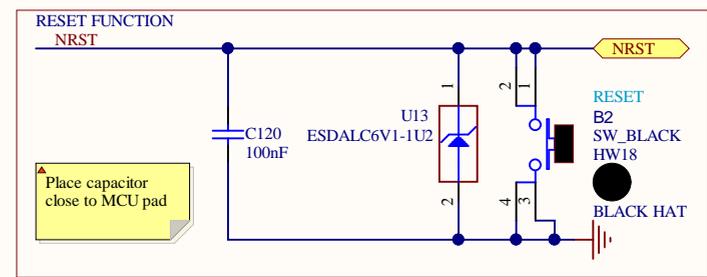
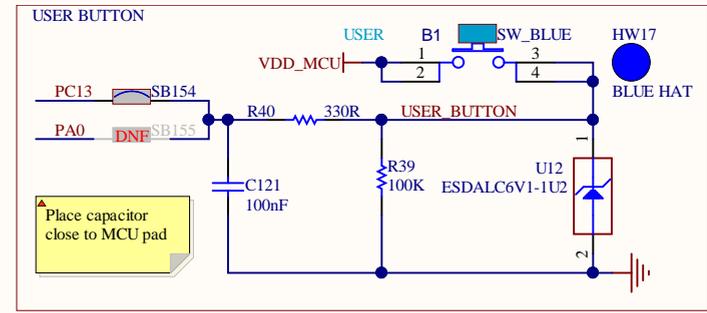
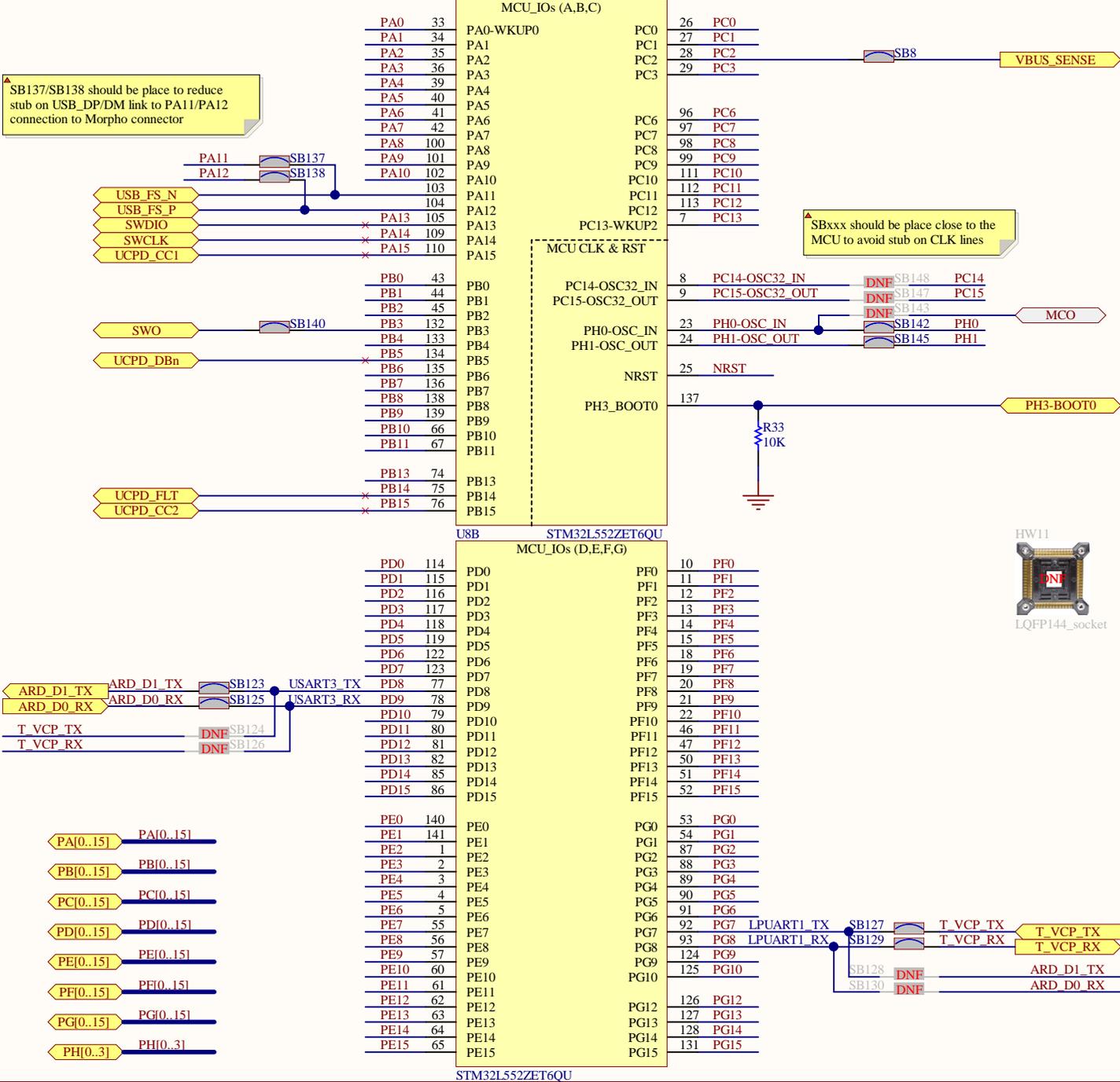


U\_ST\_LINK\_V2-1  
ST\_LINK\_V2-1.SchDoc



Cutable part on PCB

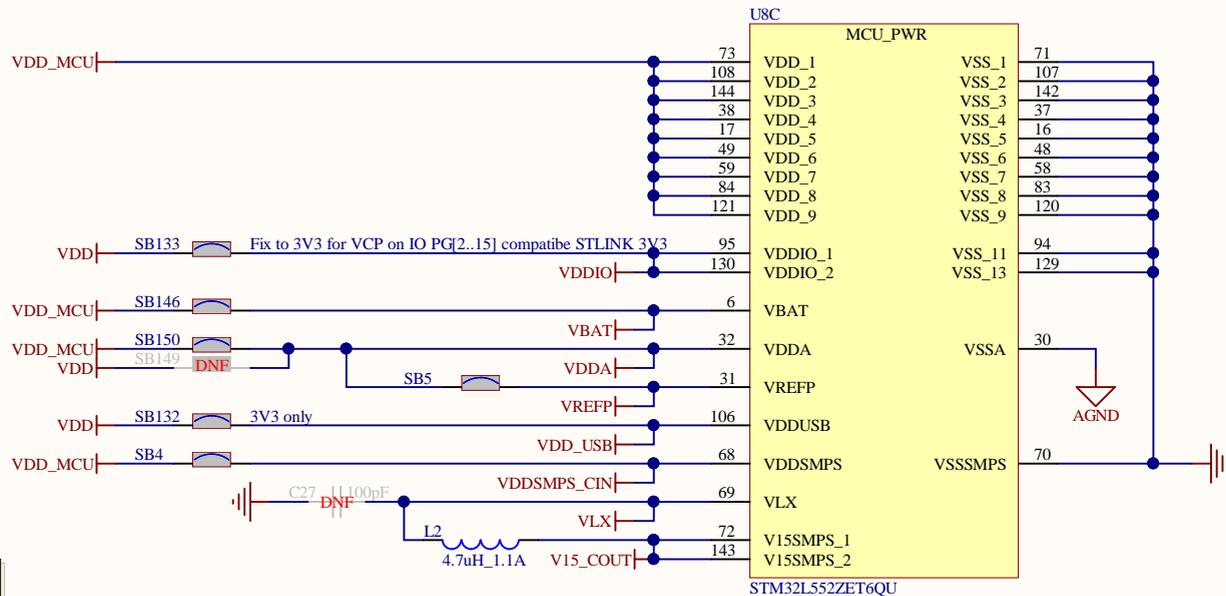
MCU IO CLK and RST



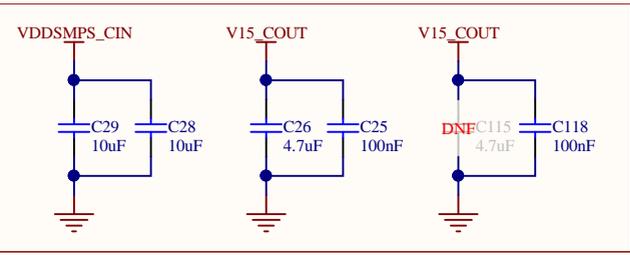
### MCU PWR SUPPLIES

Operating range:  $1V71 < VDD < 3V6$   
 Operating range:  $1V08 < VDDIO2 < 3V6$  (only for IO G[15:2])  
 Operating range:  $1V55 < VBAT < 3V6$   
 Operating range:  $1V62 < VDDA < 3V6$   
 Operating range:  $1V62 < VREF < 3V6$  (depend of VDDA)  
 Operating range:  $1V71 < VDD\_SMPS < 3V6$

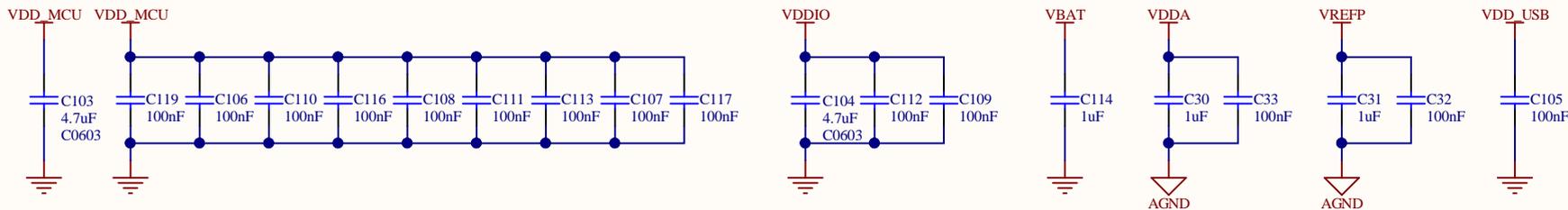
Operating range:  $3V0 < VDDUSB < 3V6$



"CIN" and "COUT" should be as closed as possible to the LQFP associated pad. COUT 10µF should be placed near L4. Or 1 couple of capacitors per pad (4.7µF / 100nF)

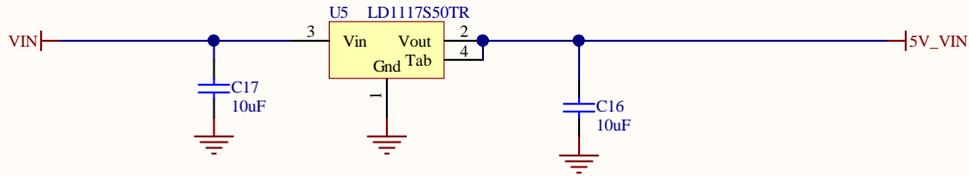


### MCU DECAPS Ceramic capacitor (Low ESR, ESR<1ohm)

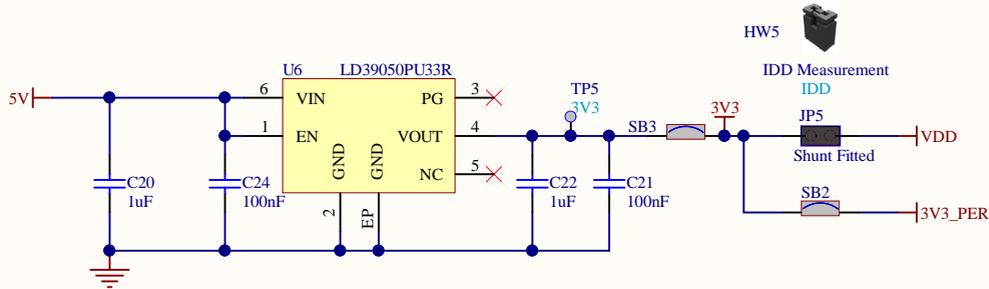




BOARD PWR: VIN / 5V (output current depend of VIN range)

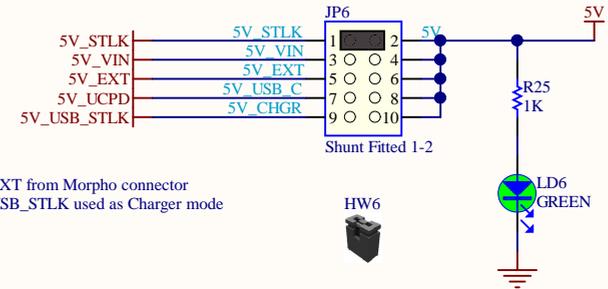


3V3 POWER SOURCE / 500mA



5V PWR SELECTION

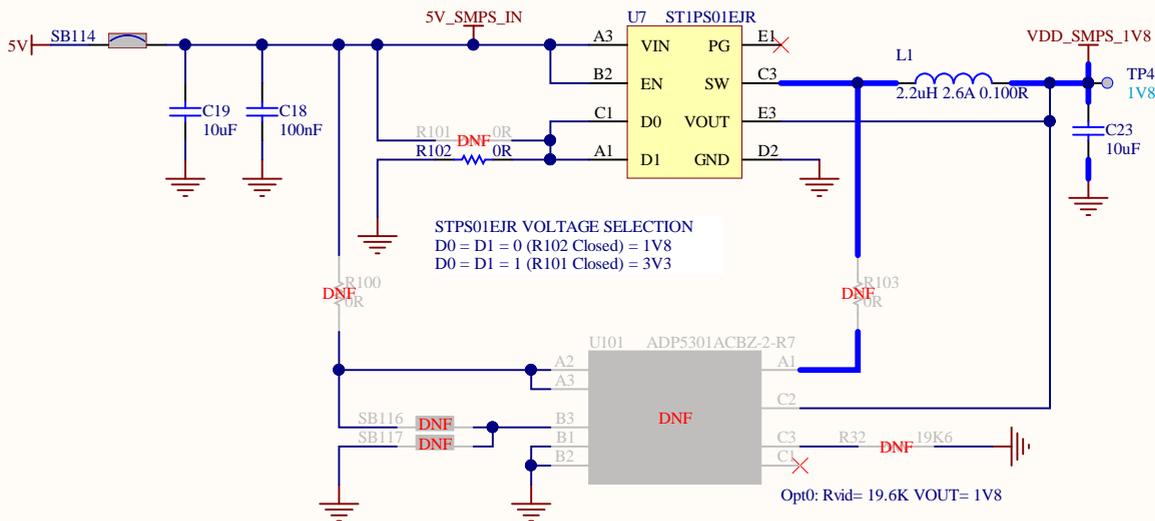
MAX CURRENT 500mA WHEN USING POWER INPUT 5V\_STLK



5V\_EXT from Morpho connector  
5V\_USB\_STLK used as Charger mode

1V8 POWER SOURCE / 400mA

U7 AND U101 ARE EXCLUSIVELY POPULATED

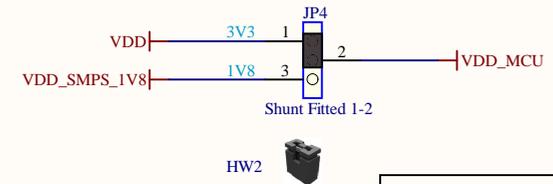


STPS01EJR VOLTAGE SELECTION  
D0 = D1 = 0 (R102 Closed) = 1V8  
D0 = D1 = 1 (R101 Closed) = 3V3

ADP5301 MODE SELECTION  
SYNC/MODE = 1 (SB116 Closed) = HYSTERESIS MODE 50mA  
SYNC/MODE = 0 (SB117 Closed) = PWM MODE 500mA

Opt0: Rvid= 19.6K VOUT= 1V8

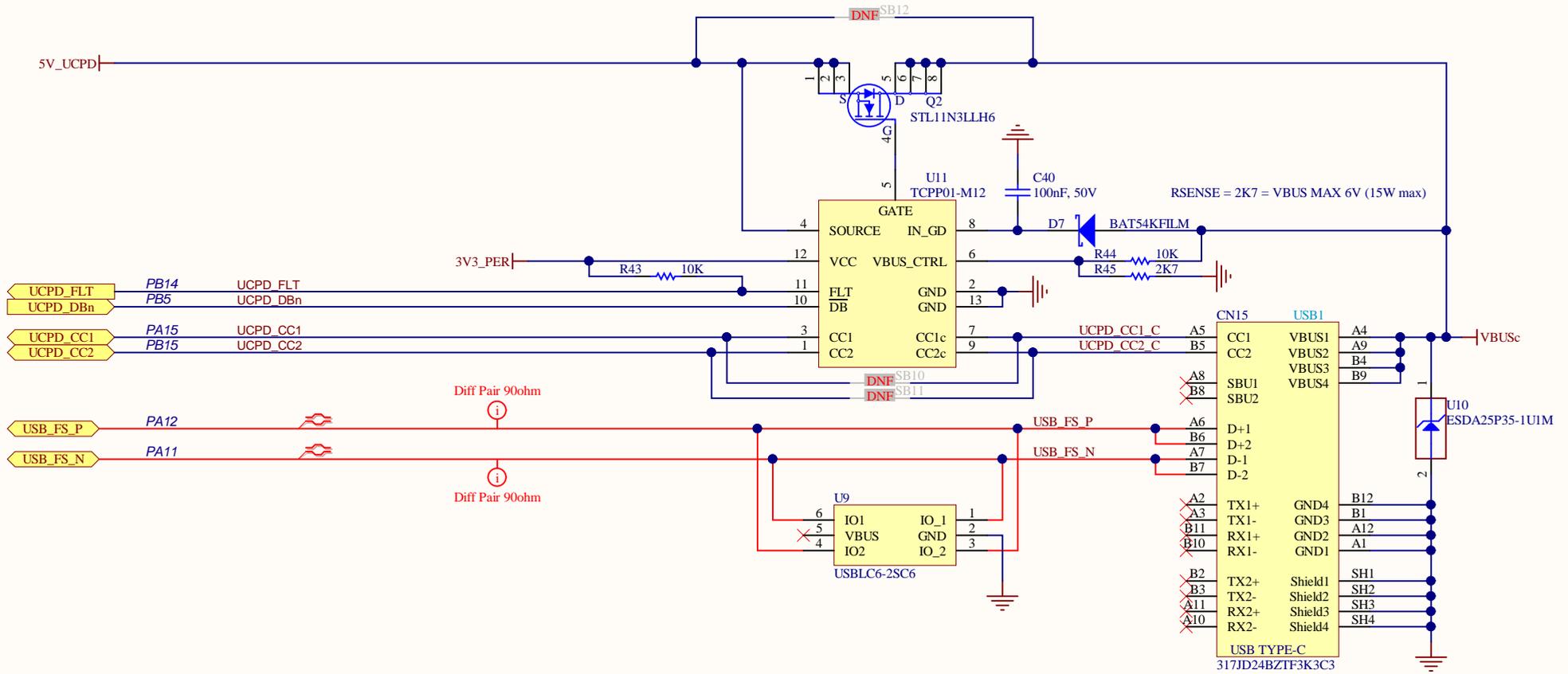
VDD\_MCU\_SELECTION AND CURRENT MEASUREMENT



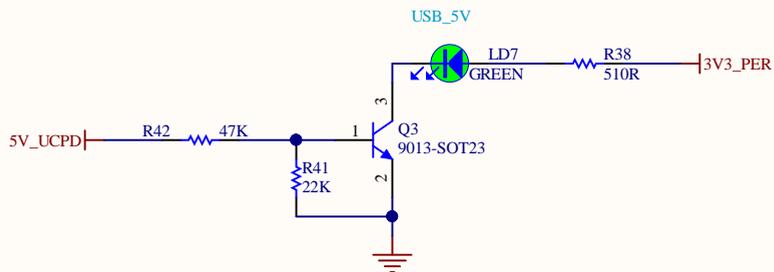
VDD_MCU table	JP4
VDD_MCU= VDD = 3V3	[1-2]
VDD_MCU= VDD_SMPS_1V8 = 1V8	[2-3]



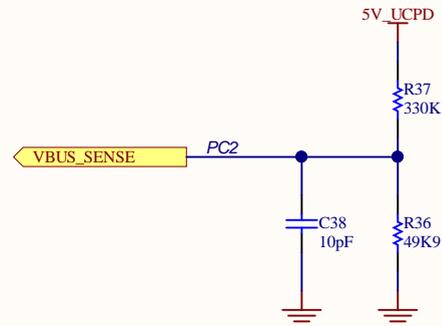
USB\_TYPE\_C CONNECTOR



5V\_USB\_LED



VBUS SENSE



Title: USB_Type_C	
Project: NUCLEO144_Q (int-SMPS)	
Variant: L552ZEQ	
Revision: C-02	Reference: MB1361
Size: A4	Date: 13-JUNE-19
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MECHANICAL PARTS

HW100

PCB

MB1361C

HW101

BOARD REF

MBxxxxx-yy-zz syywwxxxxx

HW102

BOARD CPN

Board CPN

HW3

LOGO NUCLEO

LOGO NUCLEO

HW104

LOGO ST

LOGO ST

HW105

LOGO CE

LOGO CE

HW103

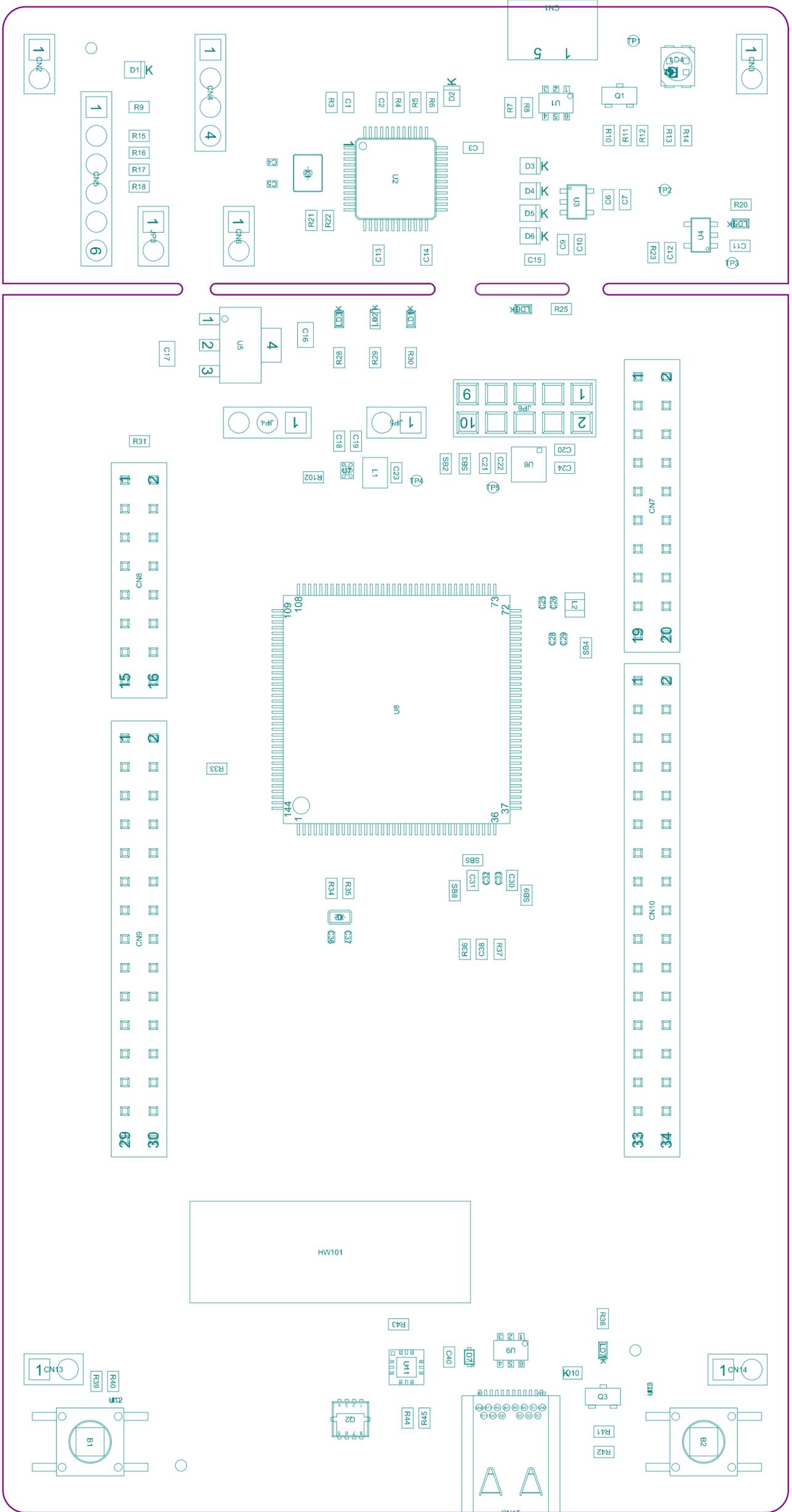
LOGO ESD

LOGO ESD

HW106

LOGO ROHS

LOGO ROHS



Project: NUCLEO144\_Q (int-SMPS)

Layer: M14-Top Assembly

Gerber: .GM14

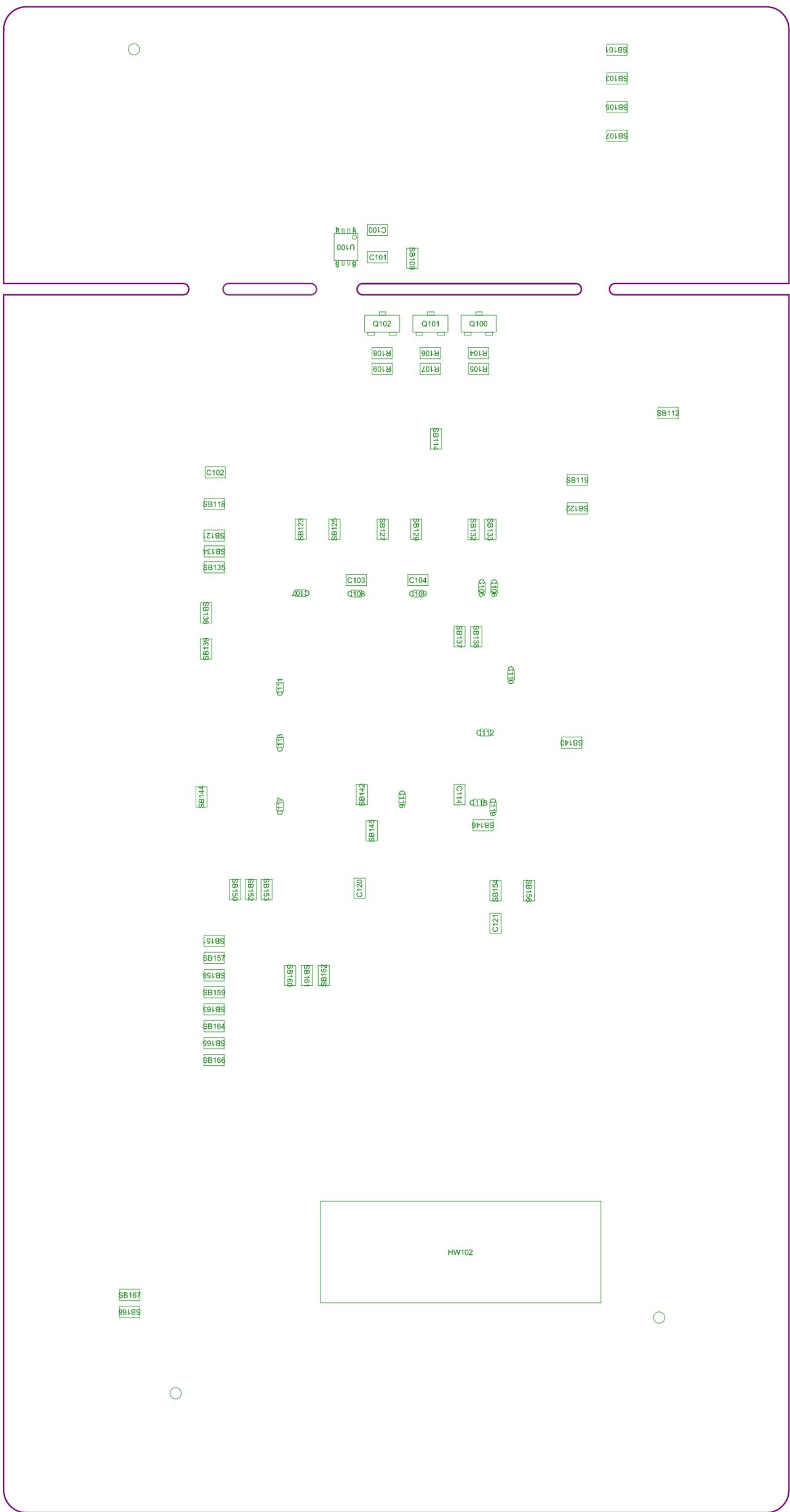
Variant: L552ZEQ

Ref: MB1361

Date: 19-FEB-21

Rev: C





Project: NUCLEO144_Q (int-SMPS)	
Layer: M15-Bottom Assembly	Gerber: .GM15
Variant: L552ZEQ	Ref: MB1361
Date: 19-FEB-21	Rev: C



